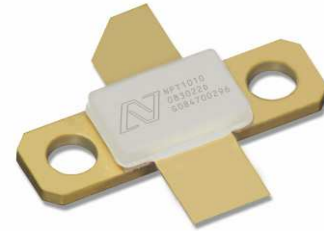


Gallium Nitride 28V, 100W RF Power Transistor

Built using the SIGANTIC® NRF1 process - A proprietary GaN-on-Silicon technology

FEATURES

- Optimized for broadband operation from DC – 2000MHz
- 100W P_{3dB} CW power at 900MHz
- 60-95 W P_{SAT} CW power from 500-1000MHz in broadband application design
- High efficiency from 14 - 28V
- 1.4 °C/W R_{TH} with maximum T_J rating of 200°C
- Robust up to 10:1 VSWR mismatch at all phase angles with no damage to the device
- Subject to EAR99 export control



DC – 2000 MHz
14 – 28 Volt
GaN HEMT



RF Specifications (CW, 900MHz): $V_{DS} = 28V$, $I_{DQ} = 700mA$, $T_A = 25^\circ C$, Measured in Nitronex Test Fixture

| Symbol | Parameter | Min | Typ | Max | Units |
|-----------|--|-------------------------|------|-----|-------|
| P_{3dB} | Average Output Power at 3dB Gain Compression | 49.0 | 50.0 | - | dBm |
| P_{1dB} | Average Output Power at 1dB Gain Compression | - | 49.0 | - | dBm |
| G_{SS} | Small Signal Gain | 18.7 | 19.7 | - | dB |
| η | Drain Efficiency at 3dB Gain Compression | 57 | 64 | - | % |
| VSWR | 10:1 VSWR at all phase angles | No damage to the device | | | |

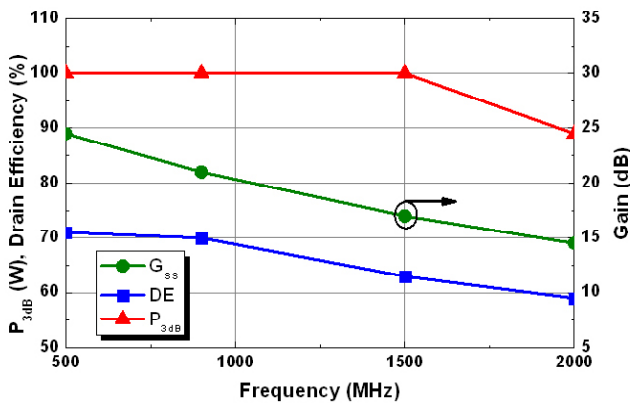


Figure 1 - Typical CW Performance in Load-Pull,
 $V_{DS} = 28V$, $I_{DQ} = 700mA$

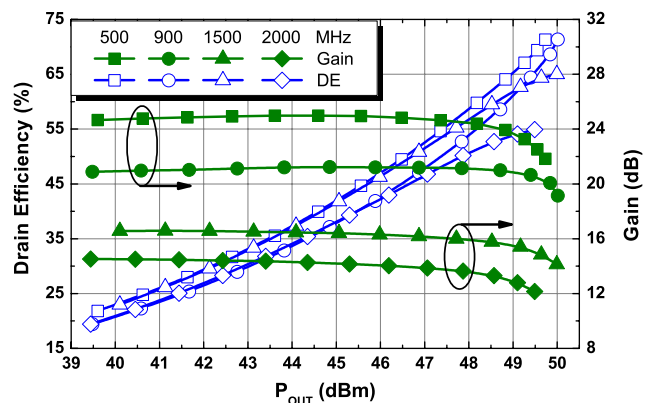


Figure 2 - Typical CW Performance in Load-Pull,
 $V_{DS} = 28V$, $I_{DQ} = 700mA$

DC Specifications: $T_A = 25^\circ\text{C}$

| Symbol | Parameter | Min | Typ | Max | Units |
|----------------------------|--|------|------|------|----------|
| Off Characteristics | | | | | |
| V_{BDS} | Drain-Source Breakdown Voltage ($V_{GS} = -8\text{V}$, $I_D = 36\text{mA}$) | 100 | - | - | V |
| I_{DLK} | Drain-Source Leakage Current ($V_{GS} = -8\text{V}$, $V_{DS} = 60\text{V}$) | - | 9 | 18 | mA |
| On Characteristics | | | | | |
| V_T | Gate Threshold Voltage ($V_{DS} = 28\text{V}$, $I_D = 36\text{mA}$) | -2.3 | -1.8 | -1.3 | V |
| V_{GSQ} | Gate Quiescent Voltage ($V_{DS} = 28\text{V}$, $I_D = 700\text{mA}$) | -2.0 | -1.5 | -1.0 | V |
| R_{ON} | On Resistance ($V_{GS} = 2\text{V}$, $I_D = 270\text{mA}$) | - | 0.13 | 0.14 | Ω |
| $I_{D,MAX}$ | Drain Current ($V_{DS} = 7\text{V}$ pulsed, 300 μs pulse width, 0.2% duty cycle) | 19.0 | 21.0 | - | A |

Thermal Resistance Specification

| Symbol | Parameter | Min | Typ | Max | Units |
|---------------|---|-----|-----|-----|---------------------------|
| θ_{JC} | Thermal Resistance (Junction-to-Case), $T_J = 180^\circ\text{C}$ | - | 1.4 | - | $^\circ\text{C}/\text{W}$ |

Absolute Maximum Ratings: Not simultaneous, $T_C = 25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Max | Units |
|-----------|--|--------------------------------|------------------|
| V_{DS} | Drain-Source Voltage | 100 | V |
| V_{GS} | Gate-Source Voltage | -10 to 3 | V |
| I_G | Gate Current | 180 | mA |
| P_T | Total Device Power Dissipation (Derated above 25°C) | 125 | W |
| T_{STG} | Storage Temperature Range | -65 to 150 | $^\circ\text{C}$ |
| T_J | Operating Junction Temperature | 200 | $^\circ\text{C}$ |
| HBM | Human Body Model ESD Rating (per JESD22-A114) | 1B (>500V) | |
| MM | Machine Model ESD Rating (per JESD22-A115) | Class A ($\leq 200\text{V}$) | |
| CDM | Charge Device Model ESD Rating (per JESD22-C101) | IV (>1000V) | |

Load-Pull Data, Reference Plane at Device Leads

$V_{DS}=28V$, $I_{DQ}=700mA$, $T_A=25^\circ C$ unless otherwise noted

Table 1: Optimum Source and Load Impedances for CW Gain, Drain Efficiency, and Output Power Performance

| Frequency (MHz) | $Z_S (\Omega)$ | $Z_L (\Omega)$ | $P_{SAT} (W)$ | $G_{SS} (dB)$ | Drain Efficiency @ P_{SAT} (%) |
|-----------------|----------------|----------------|---------------|---------------|----------------------------------|
| 500 | $2.8 + j2.2$ | $2.7 + j2.0$ | 100 | 24.5 | 71% |
| 900 | $1.1 - j0.5$ | $1.9 + j0.6$ | 100 | 21.0 | 70% |
| 1500 | $1.1 - j3.6$ | $2.0 - j1.2$ | 100 | 17.0 | 63% |
| 2000 | $1.1 - j4.9$ | $1.9 - j3.8$ | 89 | 14.5 | 59% |

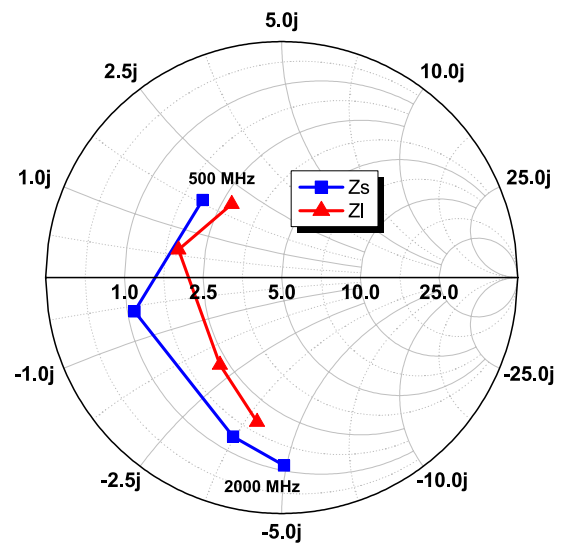
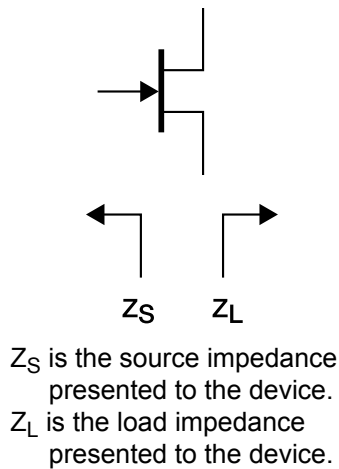


Figure 3 - Optimum Impedances for CW Performance. $Z_0 = 5 \Omega$

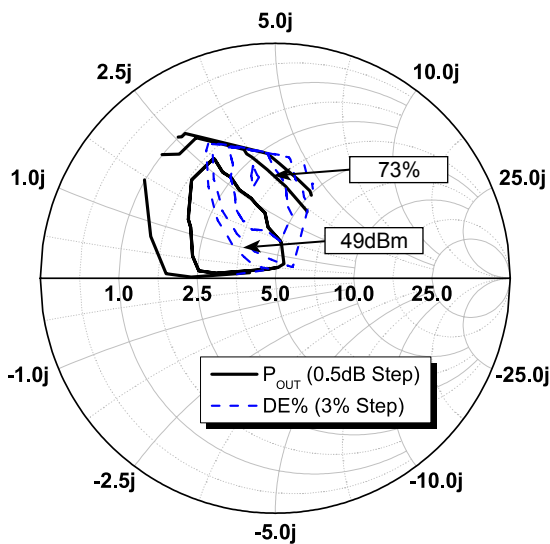


Figure 4 - Load-Pull Contours, 500MHz, $P_{IN} = 27dBm$, $Z_S = 2.8 + j2.2 \Omega$

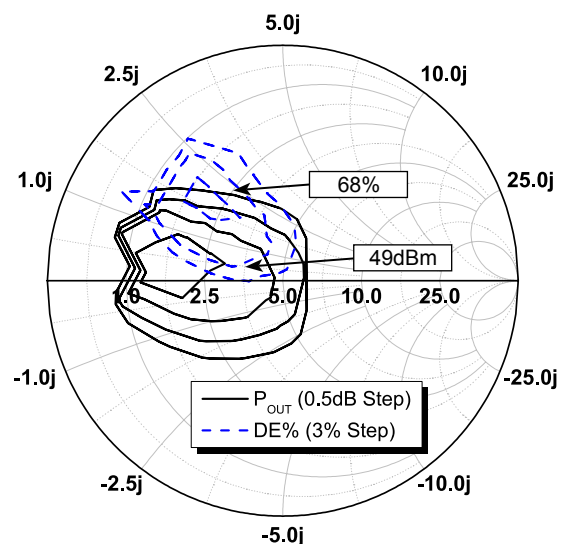


Figure 5 - Load-Pull Contours, 900MHz, $P_{IN} = 32.5dBm$, $Z_S = 1.1 - j0.5 \Omega$

Load-Pull Data, Reference Plane at Device Leads

$V_{DS}=28V, I_{DQ}=700mA, T_A=25^\circ C$ unless otherwise noted.

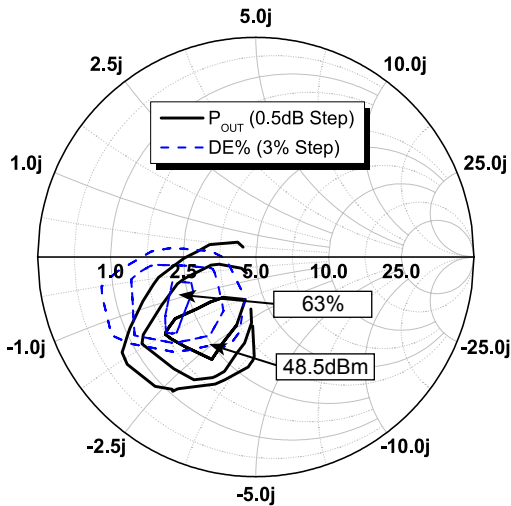


Figure 6 - Load-Pull Contours, 1500MHz, $P_{IN} = 29dBm, Z_S = 1.1 - j3.6 \Omega$

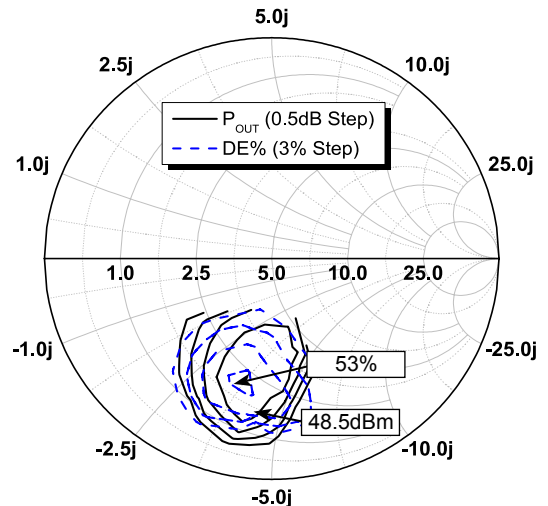


Figure 7 - Load-Pull Contours, 2000MHz, $P_{IN} = 36dBm, Z_S = 1.1 - j4.9 \Omega$

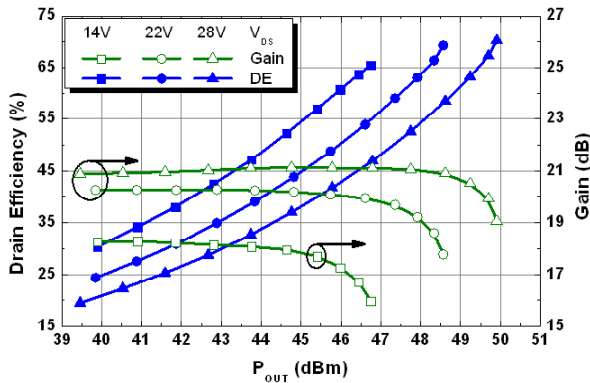


Figure 8 - Typical CW Performance Over Voltage in Load-Pull, 900MHz

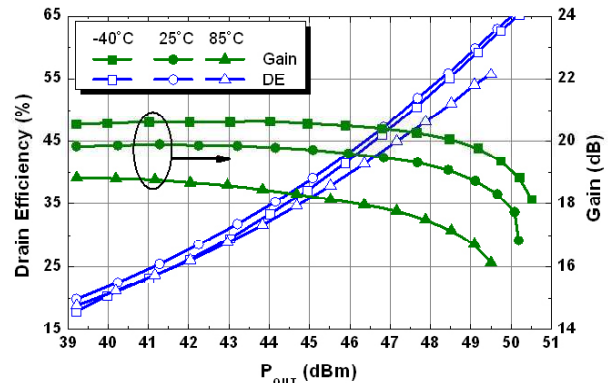


Figure 9 - Typical CW Performance Over Temperature in Nitronex Test Fixture, 900MHz

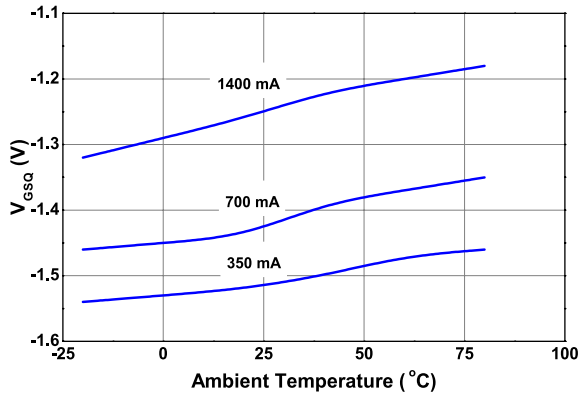


Figure 10 - Quiescent Gate Voltage (V_{GSQ}) Required to Reach I_{DQ} as a Function of Ambient Temperature, $V_{DS} = 28V$

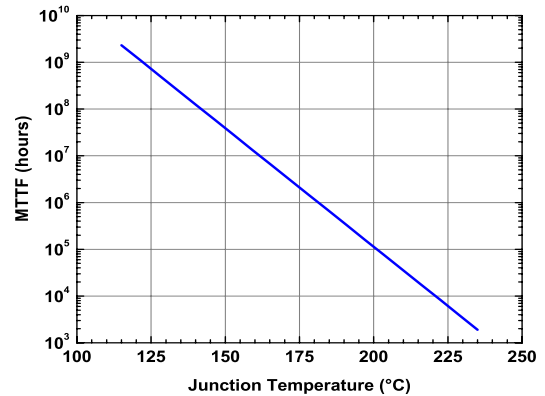


Figure 11 - MTTF of NRF1 Devices as a Function of Junction Temperature

RF Performance in 500-1000MHz Broadband Application Circuit

$V_{DS}=28V$, $I_{DQ}=700mA$, $T_A=25^{\circ}C$ unless otherwise noted



Figure 12 - Photograph of 500-1000MHz broadband application circuit for NPT1010

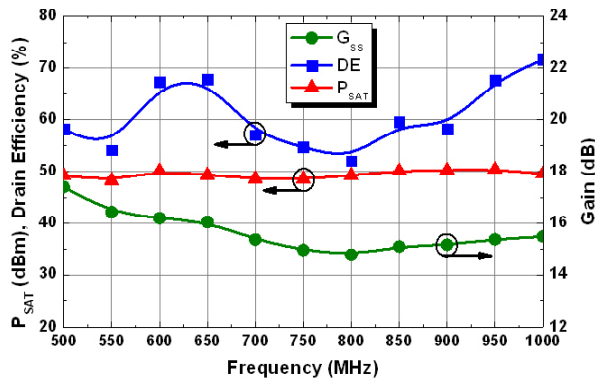


Figure 13 - CW Performance in broadband circuit. Measurements (symbols) are connected by a smoothing function (25 °C)

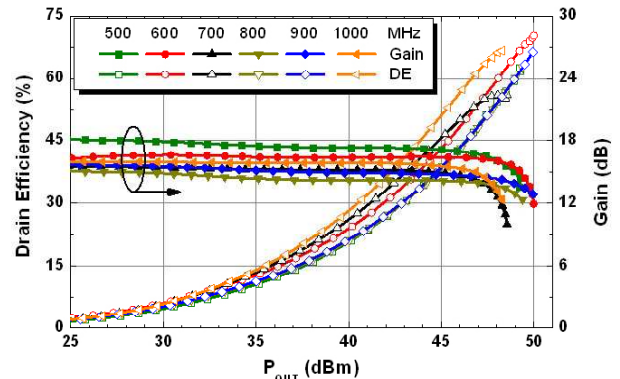


Figure 14 - CW drive up curves in broadband circuit.

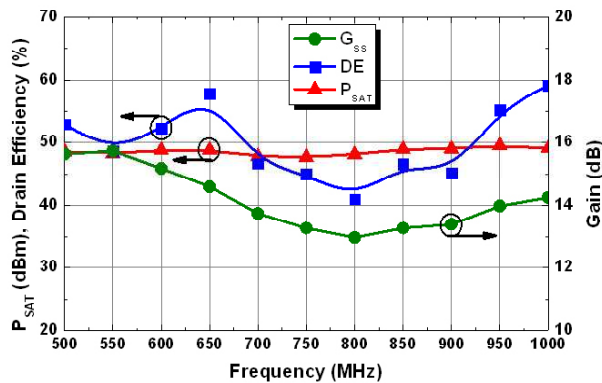


Figure 15 - CW Performance in broadband circuit. Measurements (symbols) are connected by a smoothing function (100 °C)

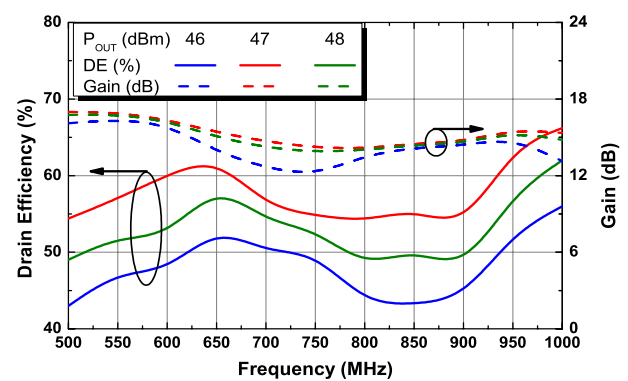


Figure 16 - CW Performance in broadband circuit at different output powers connected by a smoothing function

RF Performance in 500-1000MHz Broadband Application Circuit

$V_{DS}=28V$, $I_{DQ}=700mA$, $T_A=25^{\circ}C$ unless otherwise noted

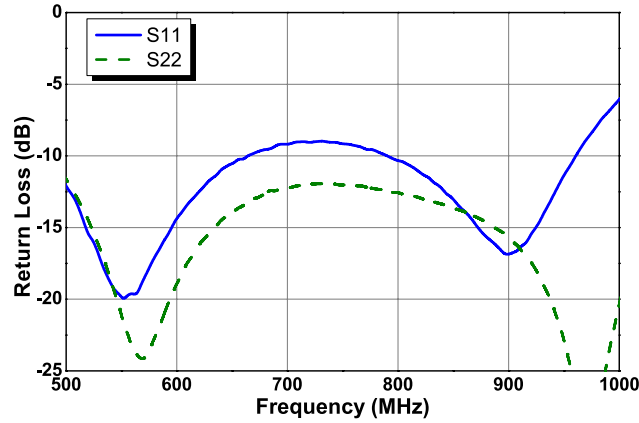


Figure 17 - Input and output return loss of the 500-1000MHz broadband application circuit, $P_{IN} = -5dBm$

Table 2: Power, gain, efficiency and temperature rise across frequency in the 500-1000MHz application circuit

| Frequency (MHz) | P_{SAT} (dBm) | P_{SAT} (W) | Drain Efficiency @ P_{SAT} (%) | G_{SS} (dB) | $T_{J,RISE}$ ($^{\circ}C$) ¹ |
|-----------------|-----------------|---------------|----------------------------------|---------------|---|
| 500 | 48.9 | 77.8 | 60 | 18.1 | 76 |
| 550 | 49.3 | 84.9 | 65 | 17.4 | 66 |
| 600 | 49.8 | 94.8 | 69 | 16.6 | 63 |
| 650 | 48.3 | 68.2 | 63 | 16.1 | 59 |
| 700 | 48.1 | 63.8 | 56 | 15.5 | 73 |
| 750 | 48.0 | 63.1 | 55 | 15.1 | 76 |
| 800 | 49.4 | 86.9 | 63 | 15.1 | 76 |
| 850 | 49.7 | 92.5 | 66 | 15.4 | 71 |
| 900 | 50.0 | 98.9 | 66 | 15.7 | 74 |
| 950 | 49.0 | 79.4 | 69 | 16.0 | 53 |
| 1000 | 48.3 | 67.1 | 67 | 16.0 | 49 |

Note 1: Temperature rise is from junction to case and is calculated from the dissipated power using an R_{TH} value of $1.4^{\circ}C/W$

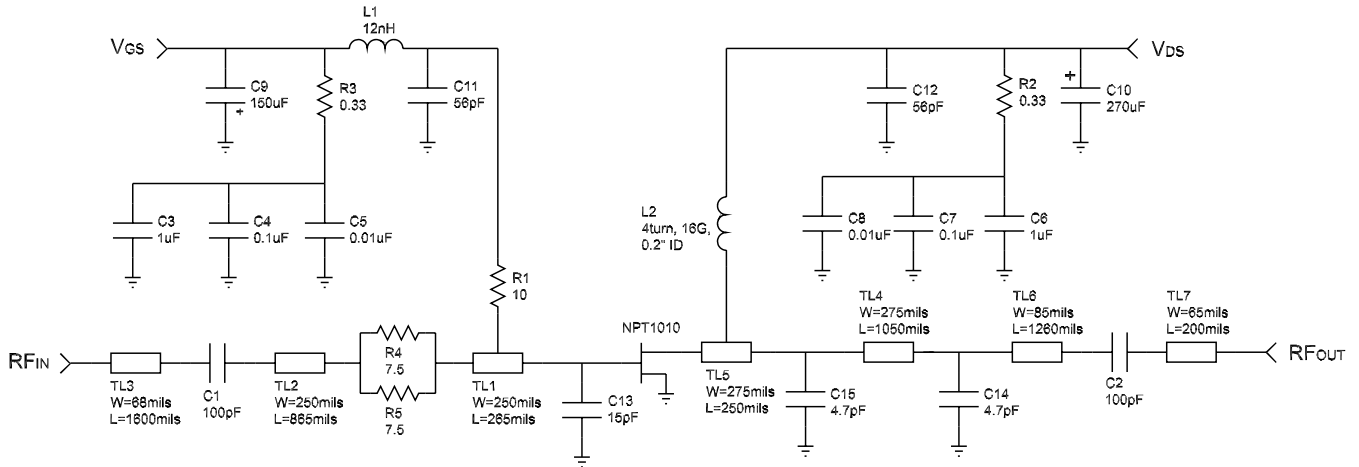


Figure 18 - Schematic of 500-1000MHz application board for NPT1010

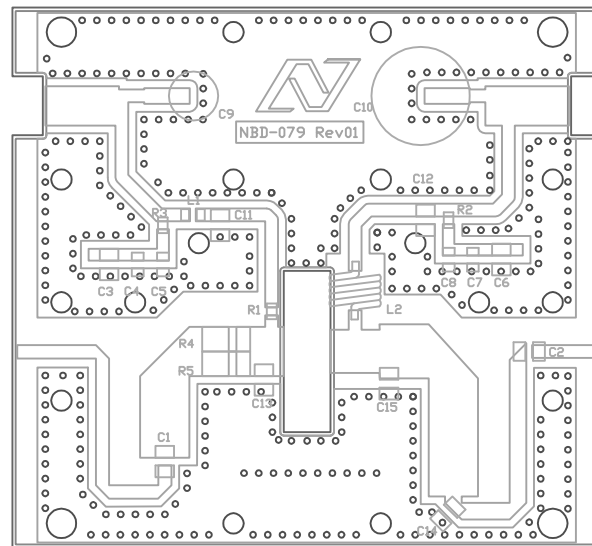


Figure 19 - Layout of 500-1000MHz application board for NPT1010

Table 3: NPT1010 500-1000MHz Application Board Build of Materials

| Name | Value | Tolerance | Size | Vendor | Vendor Number |
|---|---------------------------------|-----------|-----------|---------------------|--|
| C1 | 100pF | 5% | .11"X.11" | ATC | ATC100B101J |
| C2 | 100pF | 5% | .11"X.11" | ATC | ATC100B101J |
| C3, C6 | 1.0uF | 10% | 1812 | AVX Corp | 18121C105KAT2A |
| C4, C7 | 0.1uF | 10% | 1206 | Kemet | C1206C104K1RACTU |
| C5, C8 | 0.01uF | 1% | 1206 | AVX Corp | 12061C103KAT2A |
| C9 | 150uF | 20% | 3216(EIA) | Nichicon | UPW1C151MED |
| C10 | 270uF | 20% | 10mm(dia) | United Chmi-Con | ELXY 630ELL271MK25S |
| C11, C12 | 56pF | 1% | .11"X.11" | ATC | ATC100B560J |
| C14, C15 | 4.7pF | 1% | .11"X.11" | ATC | ATC100B4R7J |
| C13 | 15pF | 1% | .11"X.11" | ATC | ATC100B150J |
| R1 | 10 ohms | 5% | 805 | Panasonic | ERJ-6ENF10R0V |
| R2, R3 | 0.33 ohms | 1% | 805 | Panasonic | ERJ-6RQFR33V |
| R4, R5 | 7.5 ohms | 1% | 2512 | Stackpole Electron- | RHC 2512 10 1% R |
| L1 | 12nH | 5% | 805 | Coilcraft | 0805CS-120XJB |
| L2 | 4 Turn, 16G, 0.2"ID Copper Wire | | | | |
| N Connector | | | | Amphenol | 172195 |
| nbd-079_Rev1 | | | | Rogers | Rogers 6010LM 25mil, 1oz, $\epsilon_r = 10.2$ |
| Copper Heatsink | | | | | |
| BNC Connectors | | | | Tyco Electronics | 1052566-1 |
| Metric 18-8 SS Socket head Cap Screw M2.5 Thread, 8mm Length, 0.45mm Pitch | | | | McMaster Carr | 91292A012 |

NPT1010



Ordering Information¹

| Part Number | Description |
|-------------|--|
| NPT1010B | NPT1010 in AC360B-F2 Bolt-Down Package |

1: To find a Nitronex contact in your area, visit our website at <http://www.nitronex.com>

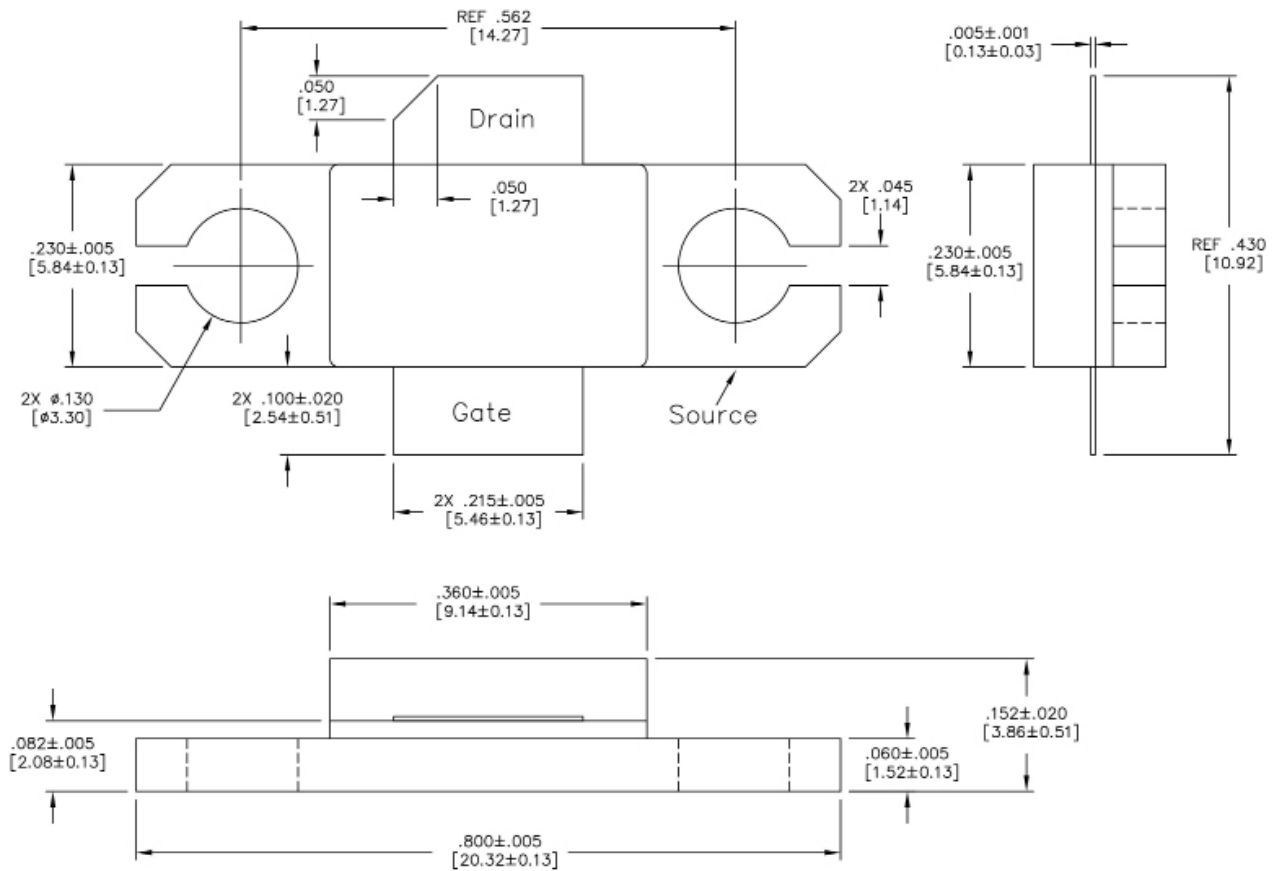


Figure 20 - AC360B-F2 Package Dimensions and Pinout (all dimensions are in inches)

Nitronex, LLC

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Additional Information

This part is lead-free and is compliant with the RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

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